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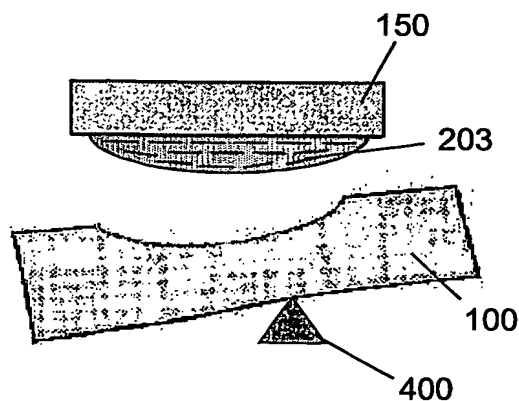
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(54) Title: LIQUID CRYSTAL COMPONENT



(57) Abstract: A method of manufacturing a component comprising liquid crystal is described. The method comprises placing a liquid crystal (200) between a substrate (150) and a mould (100), the mould (100) having a shaped surface (102). At least a portion of the shaped surface (102) has an alignment layer (110) formed on it. The substrate (150) has a first surface (152) on which is formed a bonding layer (120). Mould and substrate are brought together so as to sandwich liquid crystal between the first surface of the substrate and the shaped surface of the mould. The liquid crystal (202) is polymerised and thereby adhered to the bonding layer (120). The substrate (150) with the adhered polymerised liquid crystal (203) is removed from the mould (100).

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